

/ Descriptions

Glass Passivated Bridge Rectifiers, Reverse Voltage:50~1000V,Forward Current:25A,GBJ package.

/ Features

PCB

UL

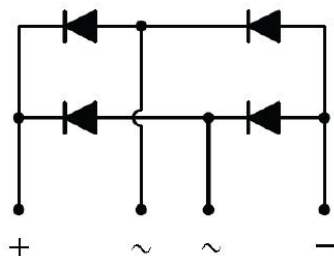
94V-0

Ideal for printed circuit board, Case material molded plastic, The plastic material has U/L flammability classification 94V-0. Halogen free product.

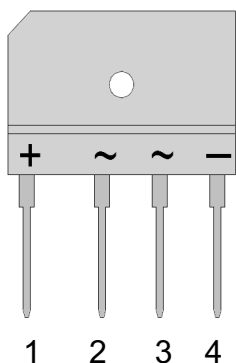
/ Applications

General purpose.

/ Equivalent Circuit



/ Pinning



PIN1 DC+ PIN2 AC PIN3 AC PIN4 DC-

/ h_{FE} Classifications & Marking

See Marking Instructions.

Parameter	Symbol	Rating							Unit
		GBJ 25005	GBJ 2501	GBJ 2502	GBJ 2504	GBJ 2506	GBJ 2508	GBJ 2510	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current (with heatsink Note 2)	$I_{F(AV)}$	25							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load (JEDEC Method)	I_{FSM}	270							A
I^2t Rating for Fusing ($t < 8.3ms$)	I^2t	300							A ² s
Typical Junction Capacitance per element (Note1)	CJ	70							pF
Typical Thermal Resistance (Note2)	$R_{\theta Jc}$	1.5							°C/W
Operation Temperature Range	T_j	-55 to +150							°C
Storage Temperature Range	T_{stg}	-55 to +150							°C

NOTE:

1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

2.Device mounted on 150mm*150mm*1.6mm Cu Plate Heatsink.

Parameter	Symbol	Test Conditions	Rating	Unit
Maximum Forward Voltage	V_F	$I_F=12.5A$	1.0	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25^\circ C$	5.0	μA

/ Electrical Characteristic Curve

FIG.1-FORWARD CURRENT DEPENDENT



FIG.3-TYPICAL JUNCTION CAPACITANCE

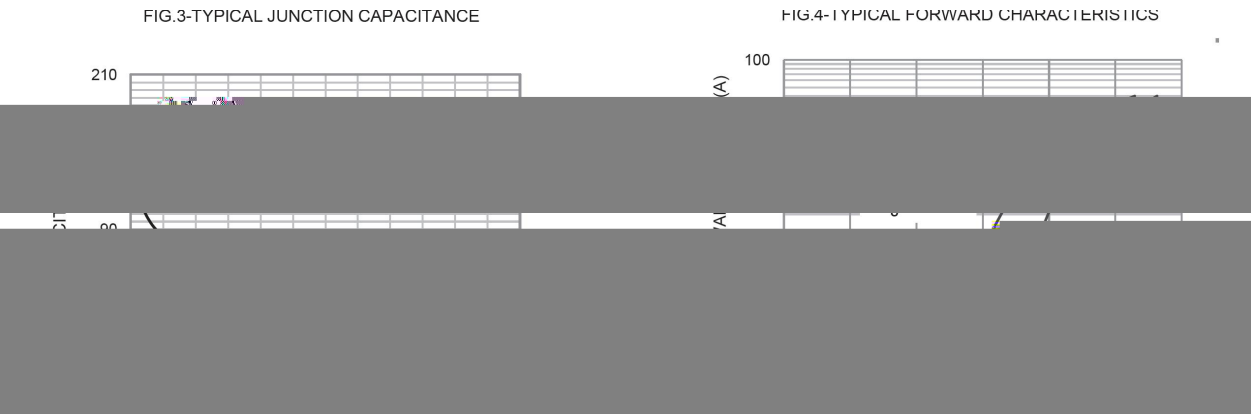
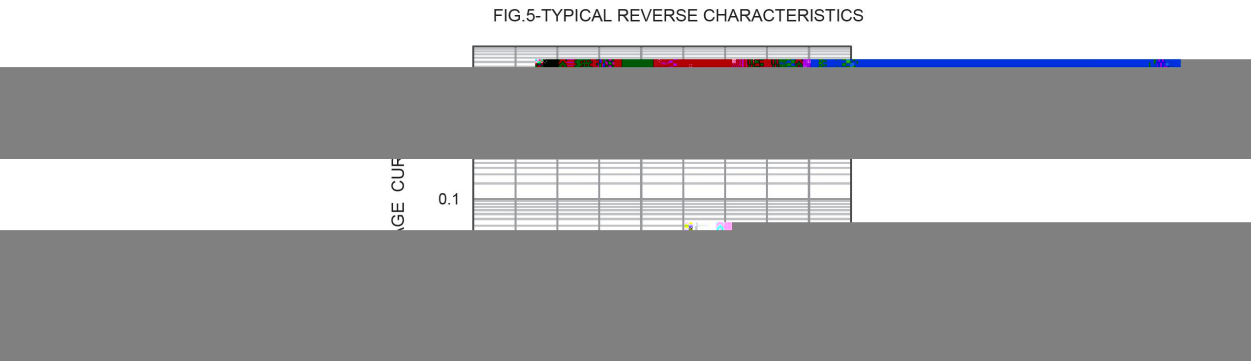


FIG.4-TYPICAL FORWARD CHARACTERISTICS

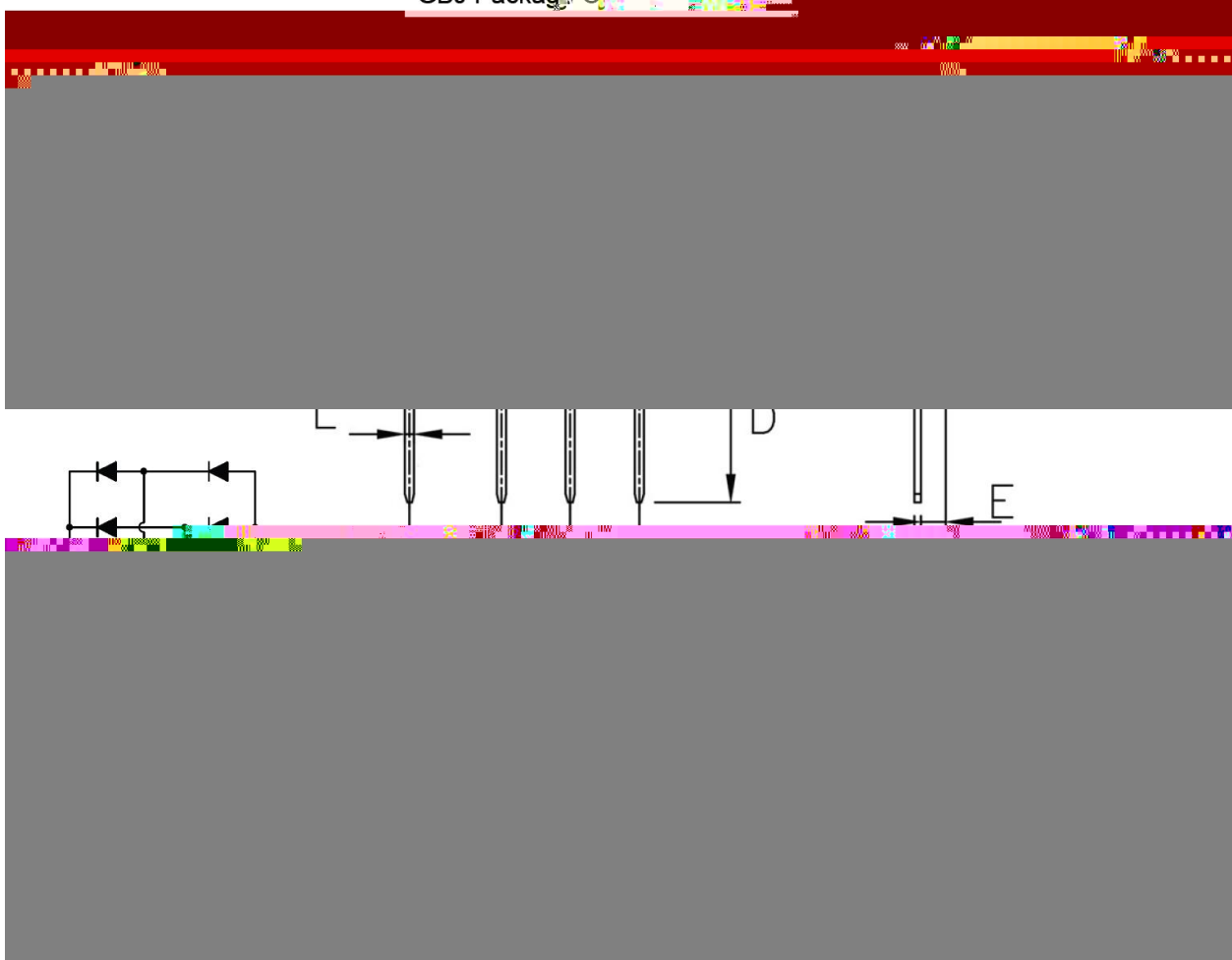


FIG.5-TYPICAL REVERSE CHARACTERISTICS

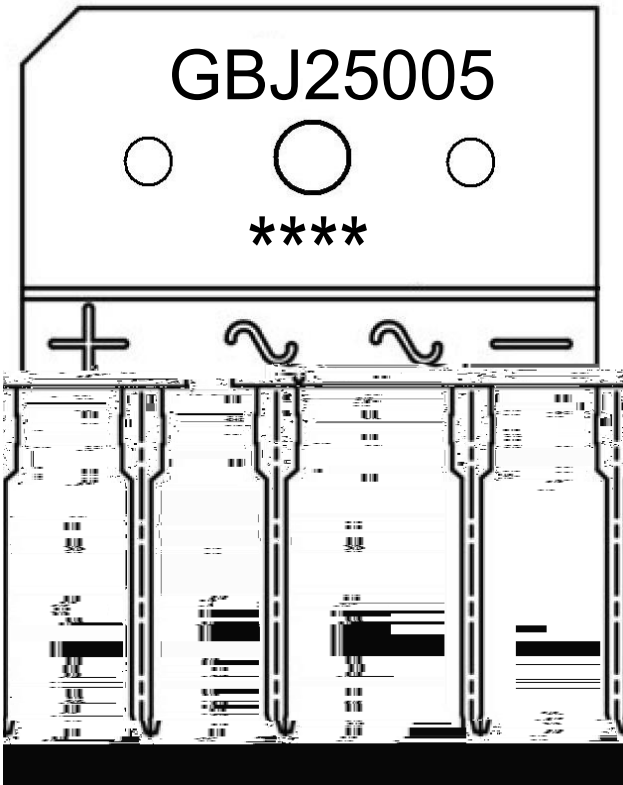


/ Package Dimensions

GBJ Package Outline Dimensions



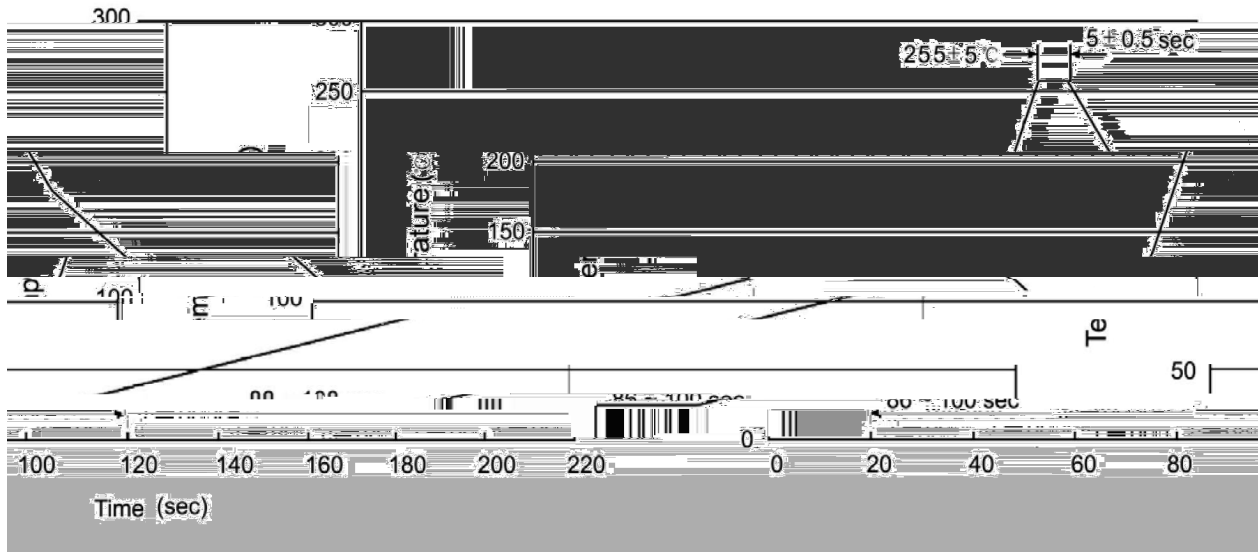
/ Marking Instructions



0	
0	0
0	0 0 0 0 0 0 0
0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	
0 0	

GBJ25005: Product Type.
****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

/ Resistance to Soldering Heat Test Conditions

温度：270±5°C

时间：10±1 sec.

Temp.:270±5°C

Time:10±1 sec

/ Packaging SPEC.

散件包装